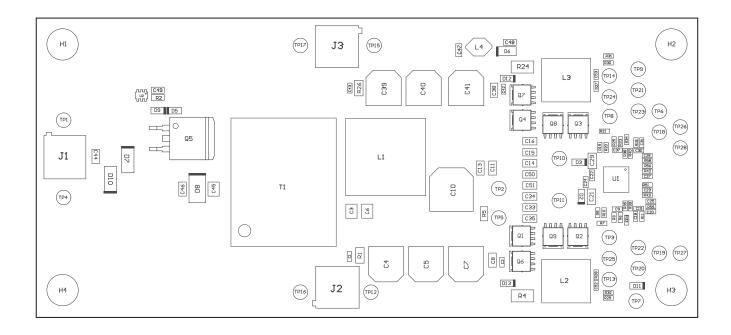
- ZZ2 ■These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP10655	REV: E1	SUN REV	: Not In VersionControl		
	TID #: PMP10655					
PLOT NAME = Top Assembly Drawing	GENERATED : 11/30/	2017 3:49:10	PM	TEXAS INSTRUMENTS		



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP10655	REV: E1	SUN REV	: Not In VersionControl		
	TID #: PMP10655					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/30/	2017 3:49:11	PM	TEXAS INSTRUMENTS		

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